



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Adrian E. Ong
Title: Layout and Use of Bond Pads and Probe for Testing of Integrated Circuits Devices
Application No.: 10/003,375
Filing Date: November 15, 2001
Examiner: Tung X. Nguyen
Group Art Unit: 2829
Confirmation No.: 4697
Law Office: Sidley Austin LLP
Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Examiner Nguyen:

Applicant submits nine (9) sheets of formal drawings, consisting of Figures 1, 2, 3, 4, 5, 6, 7, 8, and 9, in the above-named application. If there are any questions regarding these drawings, please call the undersigned at (415) 772-7428.

EXPRESS MAIL LABEL NO.:

Respectfully submitted,

EV 839 495 318 US

By:

A handwritten signature in black ink, appearing to read "Philip W. Woo".

Philip W. Woo
Attorney of Record
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PWW/rp

April 12, 2006

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